Switch-mode **Power Rectifier**

DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 35 Nanosecond Recovery Time
- Low Forward Voltage Drop
- Low Leakage
- ESD Rating:
 - Human Body Model = 3B (> 8 kV)
 - Machine Model = C (> 400 V)
- NRVUD, SRVUD and SNRVUD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

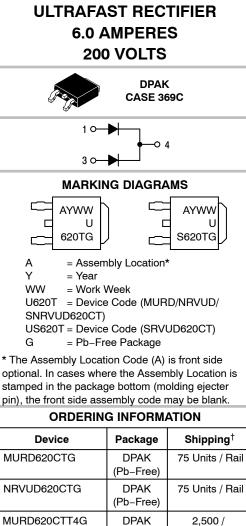
Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



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optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

Package	Shipping [†]
DPAK (Pb-Free)	75 Units / Rail
DPAK (Pb–Free)	75 Units / Rail
DPAK	2,500 /
(Pb-Free)	Tape & Reel
DPAK	2,500 /
(Pb–Free)	Tape & Reel
DPAK	2,500 /
(Pb-Free)	Tape & Reel
DPAK	2,500 /
(Pb-Free)	Tape & Reel
DPAK	2,500 /
(Pb-Free)	Tape & Reel
	DPAK (Pb-Free) DPAK (Pb-Free) DPAK (Pb-Free) DPAK (Pb-Free) DPAK (Pb-Free) DPAK (Pb-Free) DPAK

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (Rated V _R , T _C = 140°C) Per Diode Per Device	I _{F(AV)}	3.0 6.0	A
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 145°C) Per Diode	IF	6.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz)	I _{FSM}	50	А
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (Per Diode)

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ ext{ heta}JC}$	9	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	80	°C/W

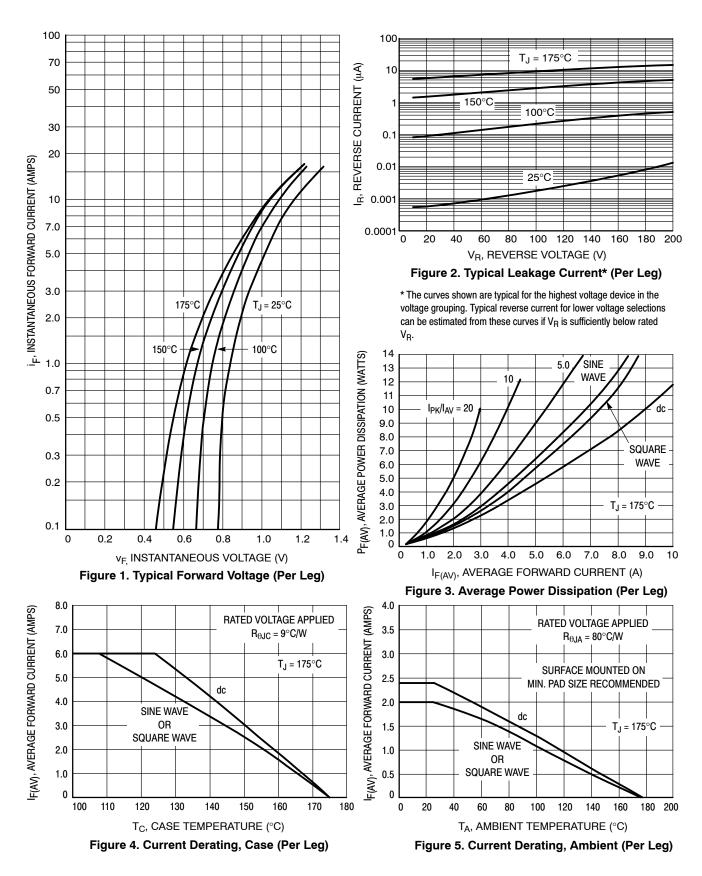
1. Rating applies when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (Per Diode)

Characteristic	Symbol	Value	Unit	
	v _F	1 0.96 1.2 1.13	V	
Maximum Instantaneous Reverse Current (Note 2) $(T_J = 25^{\circ}C, Rated dc Voltage)$ $(T_J = 125^{\circ}C, Rated dc Voltage)$	i _R	5 250	μΑ	
$ \begin{array}{l} \text{Maximum Reverse Recovery Time} \\ (I_F = 1 \text{ Amp, di/dt} = 50 \text{ Amps/} \mu \text{s}, \text{ V}_\text{R} = 30 \text{ V}, \text{ T}_\text{J} = 25^\circ\text{C}) \\ (I_F = 0.5 \text{ Amp, i}_\text{R} = 1 \text{ Amp, I}_\text{REC} = 0.25 \text{ A}, \text{ V}_\text{R} = 30 \text{ V}, \text{ T}_\text{J} = 25^\circ\text{C}) \end{array} $	t _{rr}	35 25	ns	

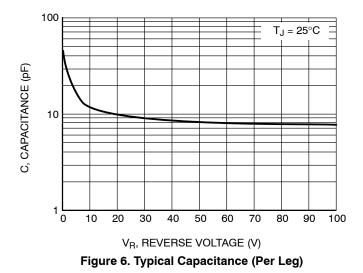
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

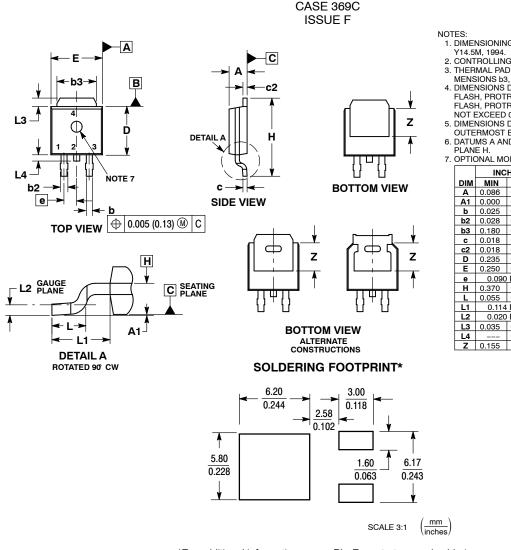


TYPICAL CHARACTERISTICS

TYPICAL CHARACTERISTICS



PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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- 1. DIMENSIONING AND TOLERANCING PER ASME
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- FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM DIAME.

7.	OPTIC	DNAL	MOLD	FEA	TURE.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29	BSC
Н	0.370	0.410	9.40	10.41
Г	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90	REF
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Ζ	0.155		3.93	

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